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U.S.S.N. 10/763,833 (DP-310317) - 2

LISTING OF THE CLAIMS:

1. – 11. (canceled)

12. (currently amended) An apparatus comprising:

a substrate having a lateral first surface and a lateral second surface, a portion of the first surface coupled to a first patterned conductive layer;

a compliant layer having a lateral first surface coupled to the first surface of the substrate and to the first patterned conductive layer, said compliant layer comprising a single, homogeneous material and having a lateral second surface;

a second patterned conductive layer having a lateral first surface coupled to the second surface of the compliant layer with no intervening layer that is significantly less compliant than the compliant layer, the second patterned conductive layer further comprising a plurality of interconnect portions extending substantially perpendicularly from the first surface thereof through the compliant layer to couple with portions of the first patterned conductive layer; and

an interconnect coupled to the compliant layer and to the conductive layer;

solder coupled to a surface mount component comprising a plurality of terminals fixedly attached with an attachment material coupled to a lateral second surface of the portions of the second conductive layer, the compliant layer and plurality of interconnects being effective to accommodate relative lateral movements between the terminals of the surface mount component and the portions of the first patterned conductive layer to reduce thermal cycling stresses in the attachment material and to the compliant layer; and

the surface mount component coupled to the compliant layer.

13. (currently amended) The apparatus ~~method~~ of claim 12, wherein an elastic modulus of the compliant layer ranges from about 0.5 megapascal (MPa) to about 2000MPa.

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14. (original) The apparatus of claim 12, wherein the compliant layer comprises one of an elastomer and a polyimide.

15. (original) The apparatus of claim 13, wherein a thickness of the compliant layer ranges from about 0.01 millimeters (mm) to about 1 mm.

16. – 18. (canceled)

19. (new) The apparatus of claim 12 wherein the attachment material is solder.

20. (new) The apparatus of claim 12 wherein the attachment material is an electrically conductive adhesive.

21. (new) The apparatus of claim 14, wherein the compliant layer comprises an elastomer having an elastic modulus within the range of about 0.5 megapascal to about 100 Megapascal.

22. (new) The apparatus of claim 14, wherein the compliant layer comprises a polyimide having an elastic modulus within the range of about 500 Megapascal to about 2000 Megapascal.